

**Remarks****Claim Rejections - 35 USC § 102**

Applicants submit that one skilled in the art would not learn to make "an electronic component carrier comprising a substrate, an electronic component and a compact label, wherein said component and said compact label are mounted on said substrate".

Moh states that "it is preferred that the application temperature is from about 100° C to 300° C greater than the softening point of glassy phase 20" (column 6 lines 45 to 48), where glassy phase 20 is defined as "an amorphous inorganic oxide material having a softening point above which the material melts or softens" (column 4 lines 53 to 55). This will inevitably lead to high label application temperatures, such as those given in the table in Column 6, which are damaging to the electronic components carried upon the electronic component carrier as claimed in the present invention.

The use of high temperatures in Moh is emphasized in the preferable temperatures outlined in the description. For example Moh states that application of the label to the substrate is "particularly useful, however, in high temperature industrial labelling applications involving elevated temperatures of at least 250°C, preferably at least 400°C, more preferably in the range from 400°C to 1800°C" (column 5 lines 42 to 45). Thus, Moh teaches application temperatures in excess of 250°C.

The Examiner states that "Moh teaches composite labels which can be attached to wide range of materials/items including electronic components such as liquid crystal display (LCD) and others". However, Applicants submit that LCDs comprise glass to which liquid crystal is applied and using the method disclosed in Moh the label would be suitable for application to the glass as glass has a high melting temperature typically in excess of 600°C.

However, if the label is being applied to a carrier carrying an electrical component such as an LED or Laser diode, as disclosed in the specification then this temperature would far exceed that recommended for storage of the LED or Laser diode, the recommended temperature for storage of LEDs and Laser diodes being below 70°C.

Applicants, therefore, submit that one skilled in the art would recognize the undesirable damage caused to electronic components caused by the high temperatures required by Moh and not use this method to apply labels to carriers holding these components. Claim 24 is thus submitted to be allowable.

Applicants submit that claims 25 to 30 are not anticipated by Moh at least by virtue of their dependencies.

Claim 31 recites a "vision system for reading a coded data symbol on an electronic component carrier". Therefore, Applicants submit that Claim 31 is not anticipated by Moh for the reasons outlined above.

Claim 32 recites "an electronic component carrier compact labelling system comprising a compact label carrying a coded identifier symbol for attachment to an electronic component carrier". Therefore, Applicants submit that Claim 32 is not anticipated by Moh for the reasons outlined above.

**Claim Rejections – 35 USC § 103**

Applicants submit that none of the references of Dobras, Gunn, Wang, Lemelson and Antognini cited by the Examiner in the Office Action of March 12 2003 teach "an electronic component carrier comprising a substrate, an electronic component and a compact label"

Dobras, Wang and Lemelson teach methods for improving scanning efficiency. Gunn provides a coding system utilizing zip codes and telephone numbers to improve efficiency of mail delivery. Antognini et al teaches an improved interface between a computer and a code printed with ink on paper. Finally, Moh teaches the addition of labels at high temperatures, which are not suitable for use on electronic component carriers for the reasons outlined above.

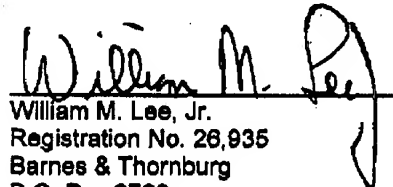
Therefore, Applicants submit that Claim 24 is non-obvious. Claims 25 to 30 are submitted to be non-obvious at least by virtue of their dependencies.

Claims 31 and 32 are for a "vision system for reading a coded data symbol on an electronic component carrier" and "an electronic component carrier compact labelling system". Therefore, Applicants submit that they are non-obvious for the reasons outlined above.

Given the above, it is submitted that, upon reconsideration, the claims are allowable, and favorable reconsideration is therefore urged.

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Respectfully submitted,



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